BAT54SWT1

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-54151736 胜特力电子(深圳) 86-755-83298787

Http://www. 100y. com. tw

Preferred Device

Dual Series Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage 0.35 Volts (Typ) @ $I_F = 10 \text{ mAdc}$
- Pb-Free Package is Available

MAXIMUM RATINGS (T_{.1} = 125°C unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	30	CV
Forward Power Dissipation @ T _A = 25°C Derate above 25°C	P _F	200 1.6	mW mW/°C
Forward Current (DC)	I _F	200 Max	mA
Junction Temperature	TJ	-55 to 125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

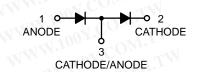
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



ON Semiconductor®

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30 VOLT DUAL SERIES SCHOTTKY BARRIER DIODES



MARKING DIAGRAM



SOT-323 CASE 419 STYLE 9



B8 = Device Code

M = Date Code*

Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

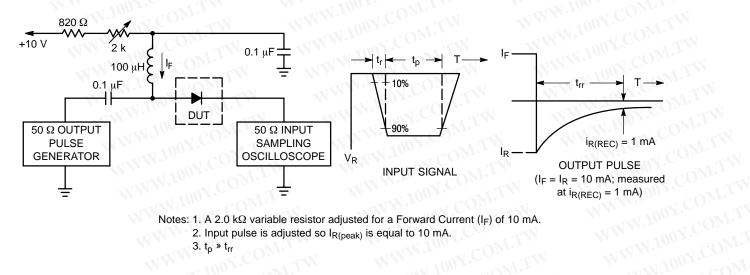
Device	Package	Shipping [†]		
BAT54SWT1	SOT-323	3000 / Tape & Reel		
BAT54SWT1G	SOT-323 (Pb-Free)	3000 / Tape & Reel		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (EACH DIODE)

Reverse Breakdown Voltage $(I_R = 10 \mu A)$ Total Capacitance	V _{(BR)R}	30	W -	_	V
Total Canacitance			.=1		
$(V_R = 1.0 \text{ V}, f = 1.0 \text{ MHz})$	Ст	V.COM	7.6	10	pF
Reverse Leakage (V _R = 25 V)	IR	OY.EON	0.5	2.0	μAdc
Forward Voltage (I _F = 0.1 mAdc)	V _F	100X-C	0.22	0.24	Vdc
Forward Voltage (I _F = 30 mAdc)	V _F	1 100 X.C	0.41	0.5	Vdc
Forward Voltage (I _F = 100 mAdc)	V _F	N.100X	0.52	0.8	Vdc
Reverse Recovery Time $(I_F = I_R = 10 \text{ mAdc}, I_{R(REC)} = 1.0 \text{ mAdc}, Figure 1)$	t _{rr}	MN 700	Y.COM	5.0	ns
Forward Voltage (I _F = 1.0 mAdc)	V _F	M. 7.	0.29	0.32	Vdc
Forward Voltage (I _F = 10 mAdc)	V _F	WWW.	0.35	0.40	Vdc
Forward Current (DC)	l _F	WANN	- 0-11Y	200	mAdc
Repetitive Peak Forward Current	I _{FRM}	-TW	1.10	300	mAdc
Non-Repetitive Peak Forward Current (t < 1.0 s)	I _{FSM}	WW	W. <u>r</u> 00	600	mAdc



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
- 3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

WWW.100Y.COM.TW

BAT54SWT1

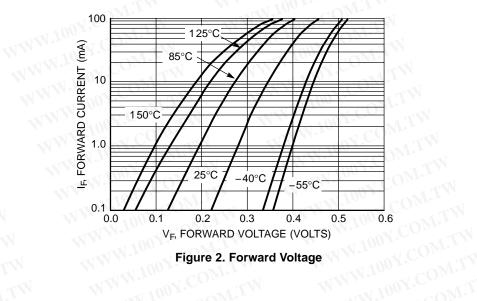


Figure 2. Forward Voltage

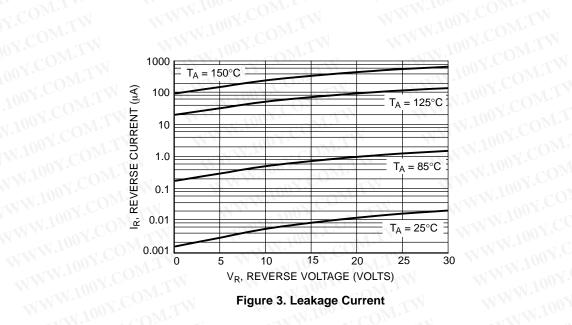
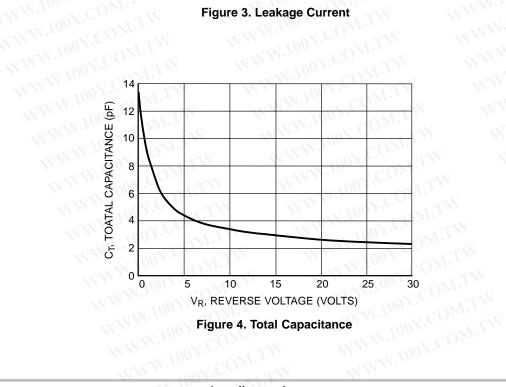


Figure 3. Leakage Current

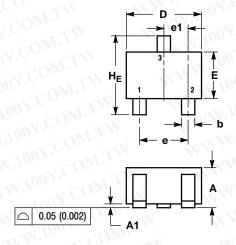


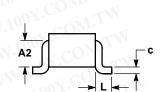
WW.100Y.C

BAT54SWT1

PACKAGE DIMENSIONS

SOT-323 (SC-70) CASE 419-04 ISSUE M





NOTES:

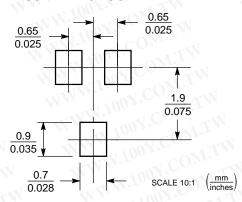
- 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			,	INCHES		
DIM	MIN	MOM	MAX	MIN	MOM	MAX	
A	0.80	0.90	1.00	0.032	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A2		0.7 REF	_		0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016	
С	0.10	0.18	0.25	0.004	0.007	0.010	
D	1.80	2.10	2.20	0.071	0.083	0.087	
E	1.15	1.24	1.35	0.045	0.049	0.053	
е	1.20	1.30	1.40	0.047	0.051	0.055	
e1	0.65 BSC			0.026 BSC			
L ₌	0.425 REF			0.017 REF			
HE	2.00	2.10	2.40	0.079	0.083	0.095	

STYLE 9: PIN 1. ANODE

2. CATHODE 3. CATHODE-ANODE

SOLDERING FOOTPRINT



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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